

MICRO X-RAY COMPUTED TOMOGRAPHY STUDY OF ADHESIVE BONDS IN WOOD

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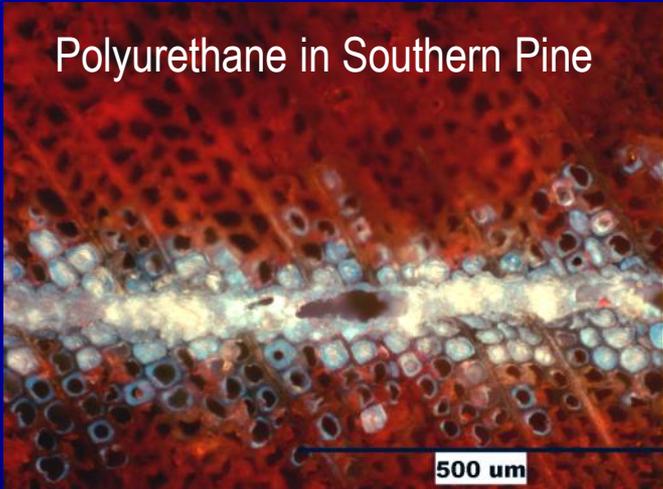
Advanced Photon Source, ANL, Argonne, Illinois

SWST 2015 International Convention

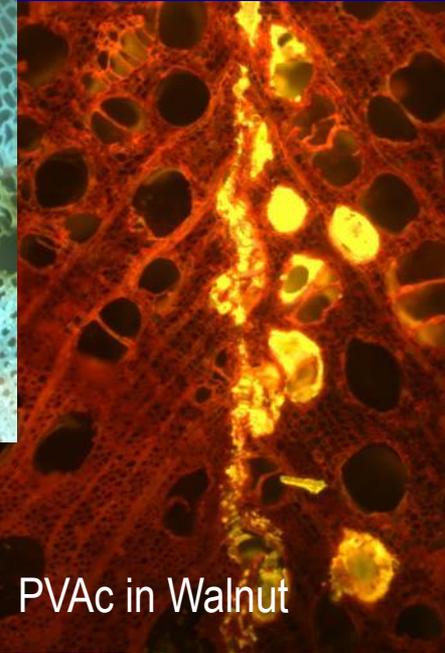
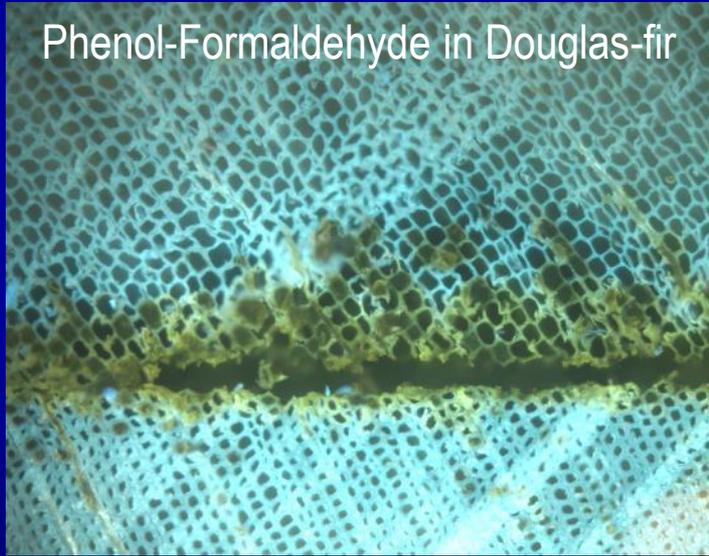
Jackson Lake Lodge, Grand Teton National Park, Wyoming USA

June 2015

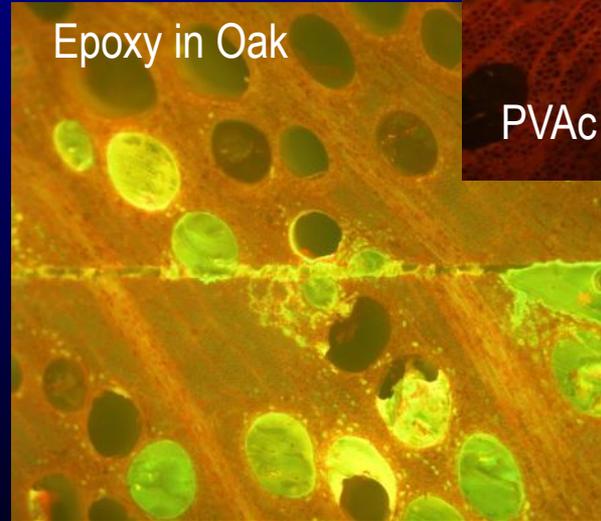
Polyurethane in Southern Pine



Phenol-Formaldehyde in Douglas-fir

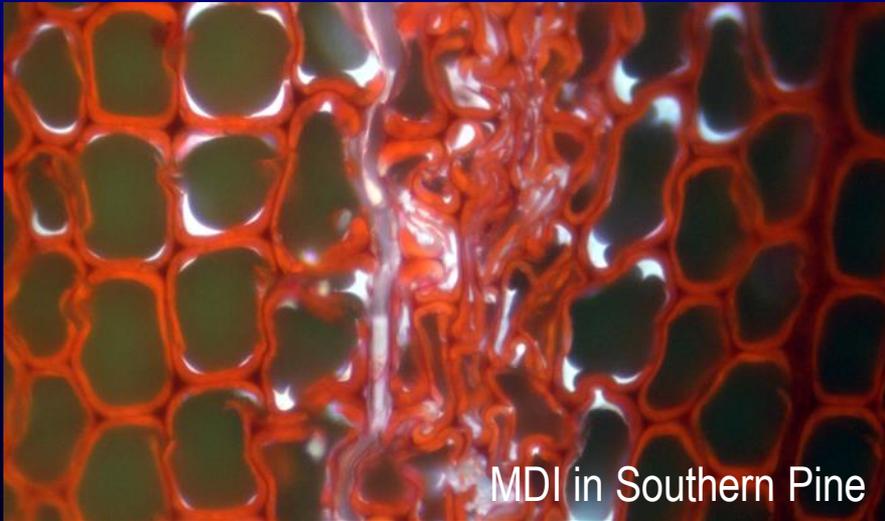


Epoxy in Oak



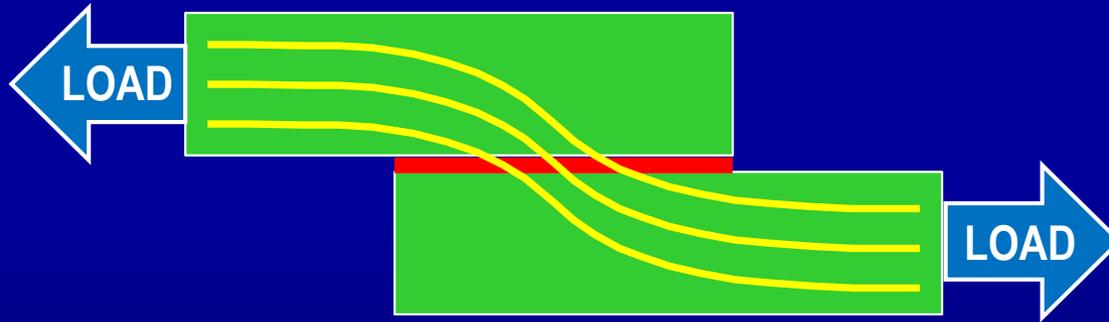
PVAc in Walnut

MDI in Southern Pine



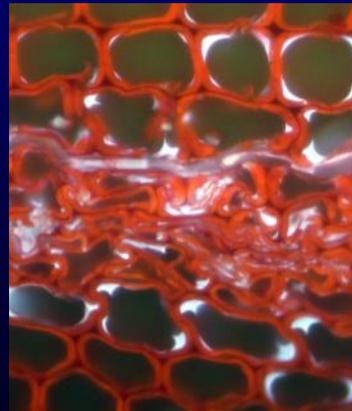
All fluorescence micrographs shown in cross-section view (RT plane) of parallel laminated wood

What does adhesive do?

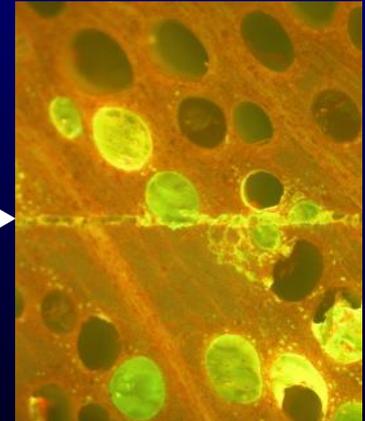


Transfers stress from one substrate to the next.

Does adhesive penetration influence stress transfer?



← Bondline →



Research Goal:

Develop a numerical model to simulate wood-composite joint-performance that quantitatively accounts for the role of adhesive penetration

Sponsors:

NSF Industry/University Cooperative Research Center for Wood-Based Composites

USDA National Institute of Food and Agriculture

Collaborators:

- *Oregon State University*

Project leadership, mechanical testing, specimen prep., modeling

- *Advance Photon Source, Argonne National Laboratory*

Tomography beamline access on synchrotron device

- *ETH Zürich, Switzerland*

Mechanical test device

- *US Forest Products Laboratory*

Nano-indentation & x-ray fluorescence microscopy

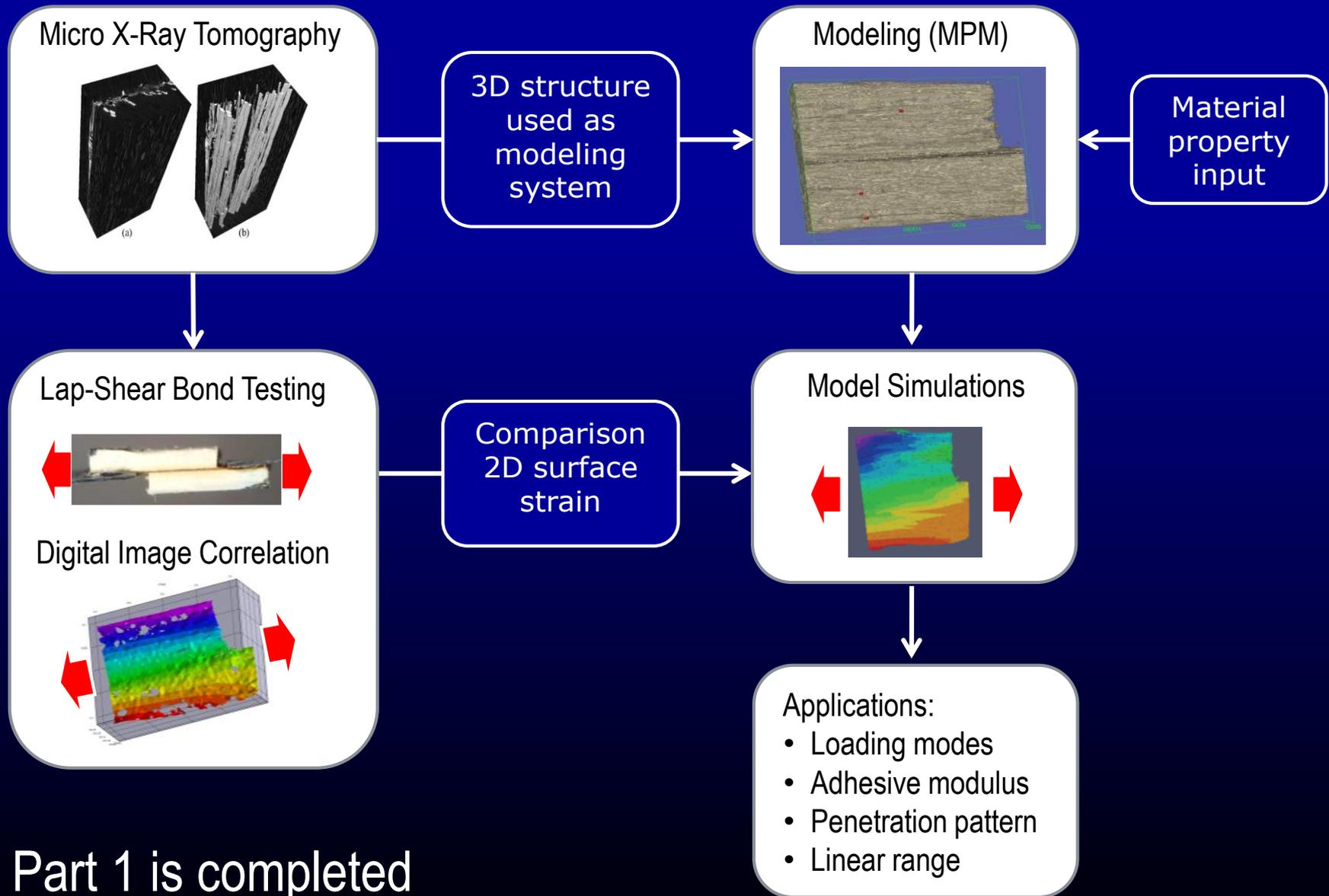
- *Member organizations of the Wood-Based Composites Center*

Resin formulation and technical guidance

Outline:

- Methodology
 - Part 1 – Linear elastic model development
 - Part 2 – Non-linear model development
 - Part 3 – Moisture durability of bondline (see McKinley poster)
- *In situ* mechanical testing of bondline during XCT
- Digital volume correlation
- Examples of modeling results

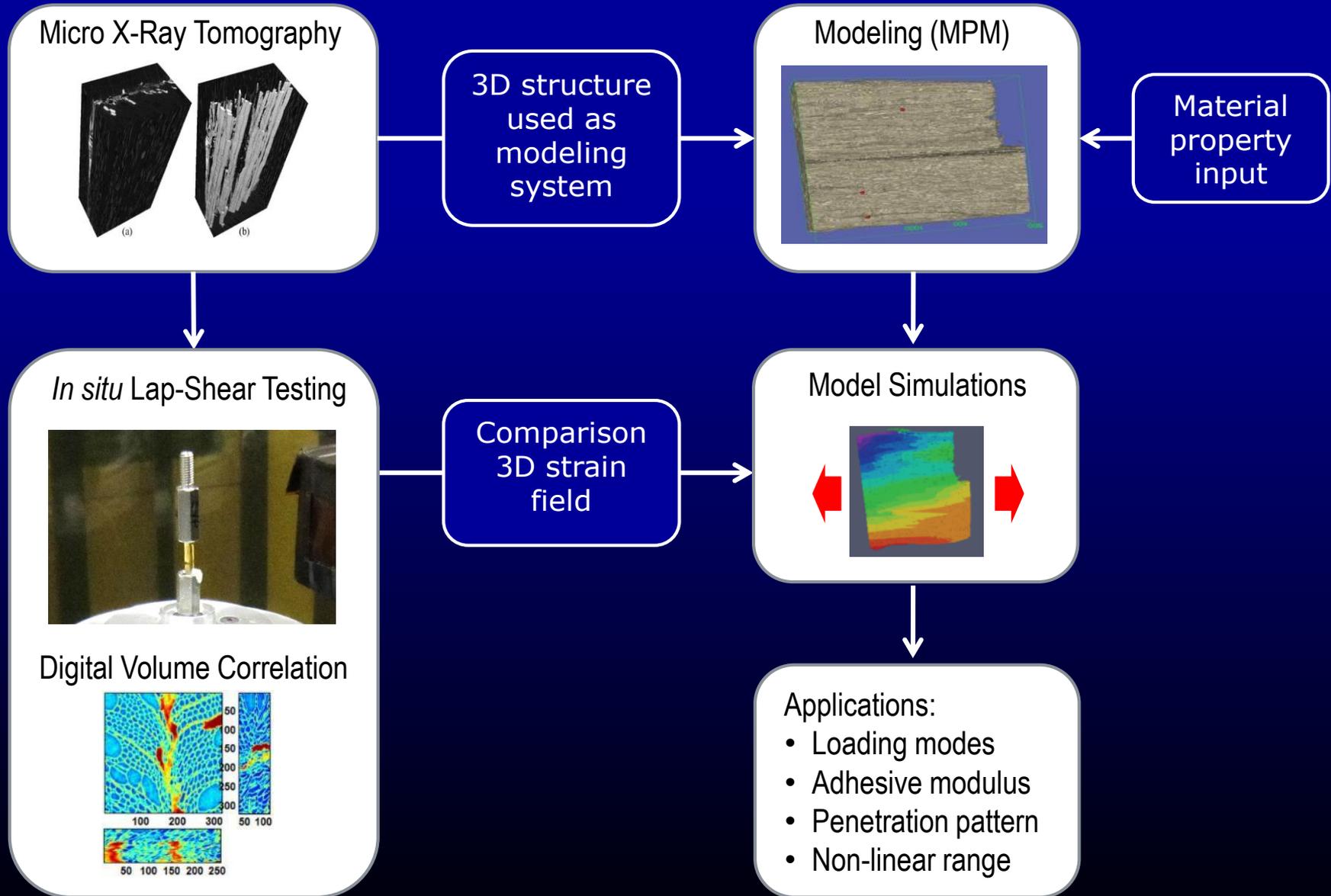
Methodology – Part 1 Linear-elastic model



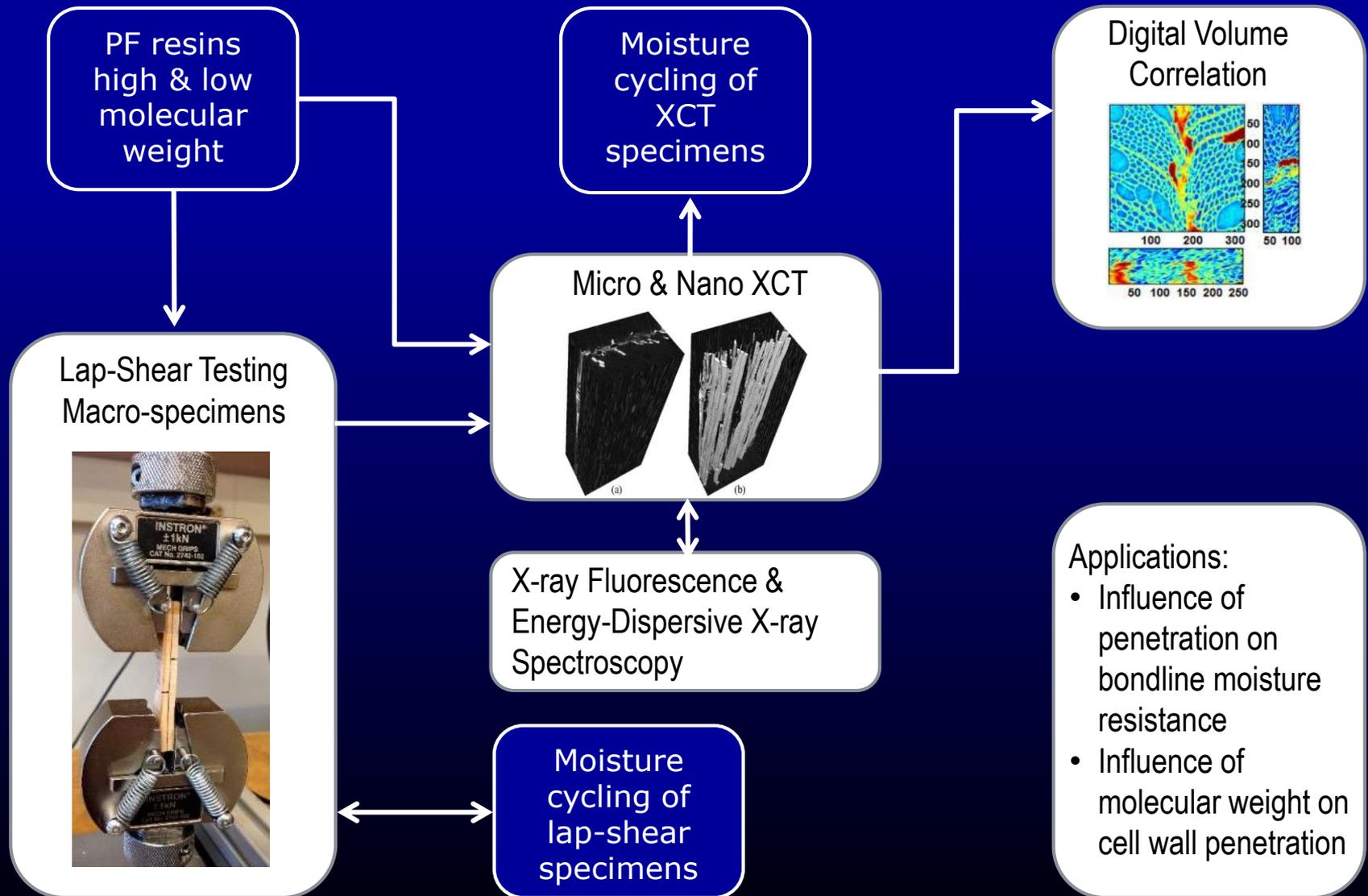
Part 1 is completed

Methodology – Part 2

Non-linear model



Methodology – Part 3 Moisture durability

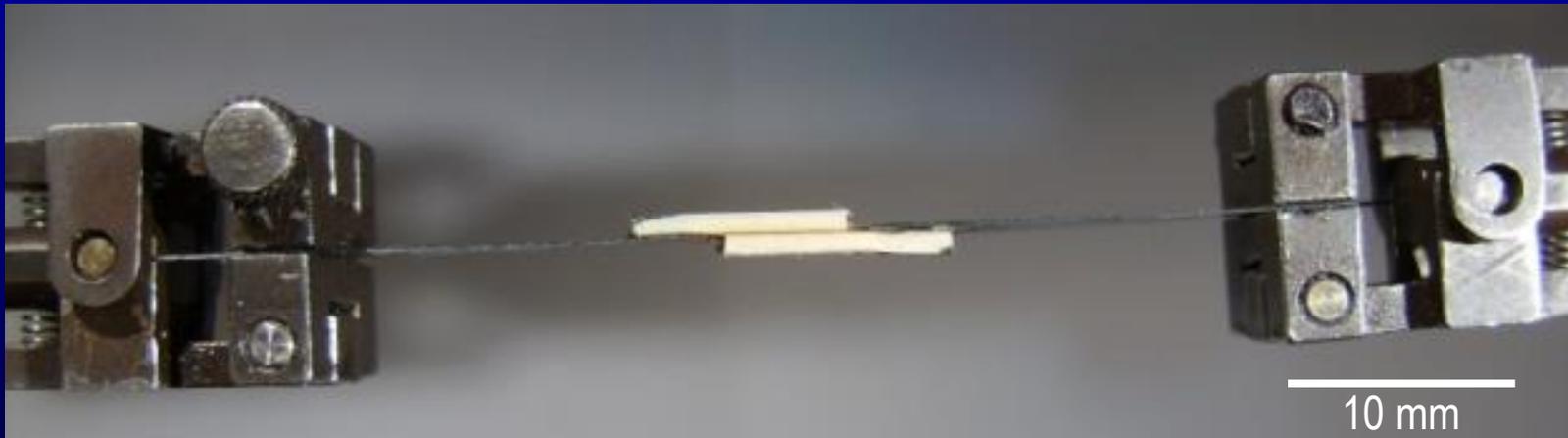


Micro-Bond Testing

Non-destructive, linear range, tensile loading

Same specimen used for micro X-ray computed tomography

DIC of surface deformation compared to model results



Load Cell: +/- 100 N (+/- 0.1 N)

Displacement: 0.16 mm (+/- 0.0001 mm)

Micro-Bond Testing

During step-wise XCT scan

Camera

Lens

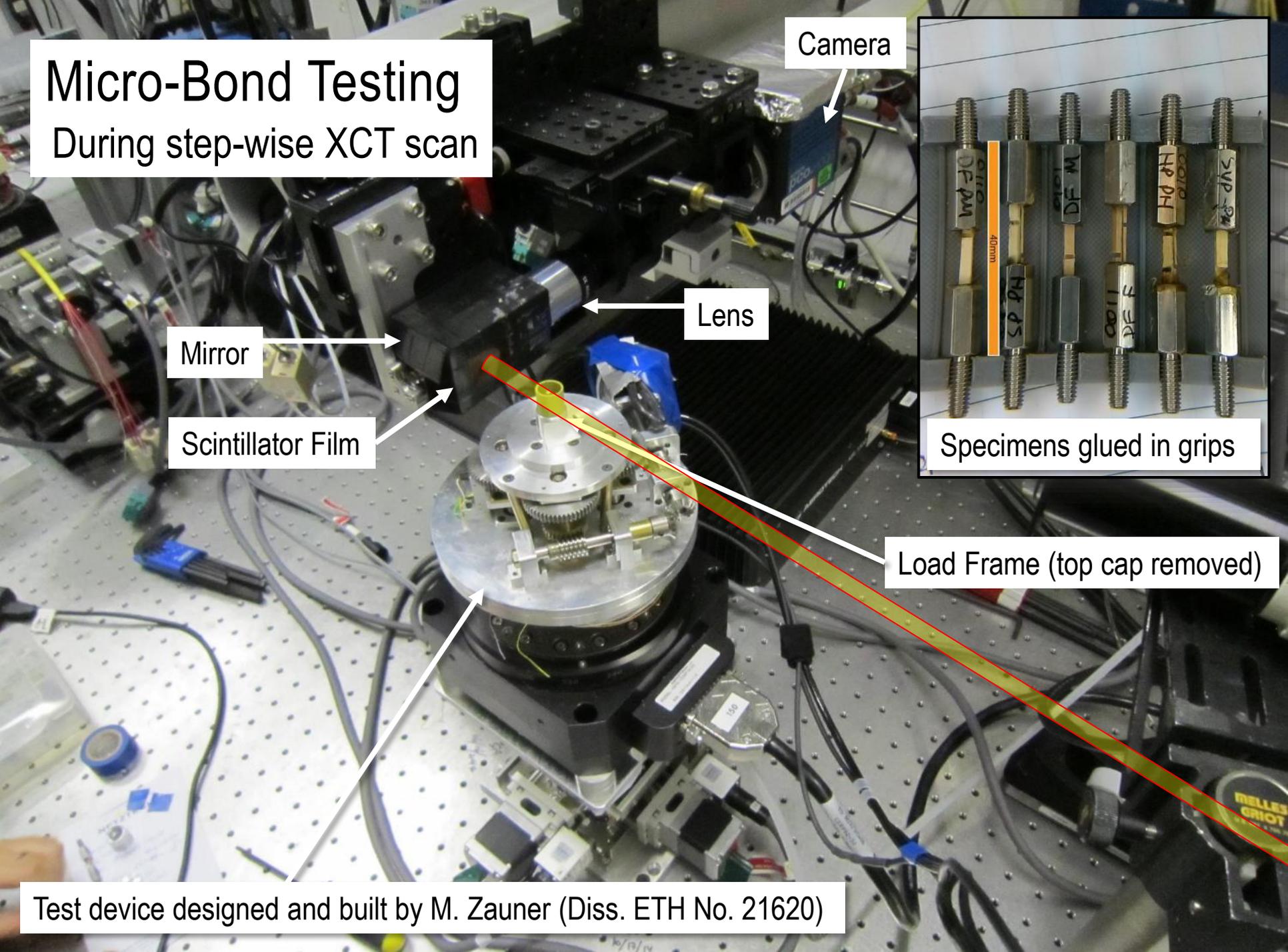
Mirror

Scintillator Film

Load Frame (top cap removed)

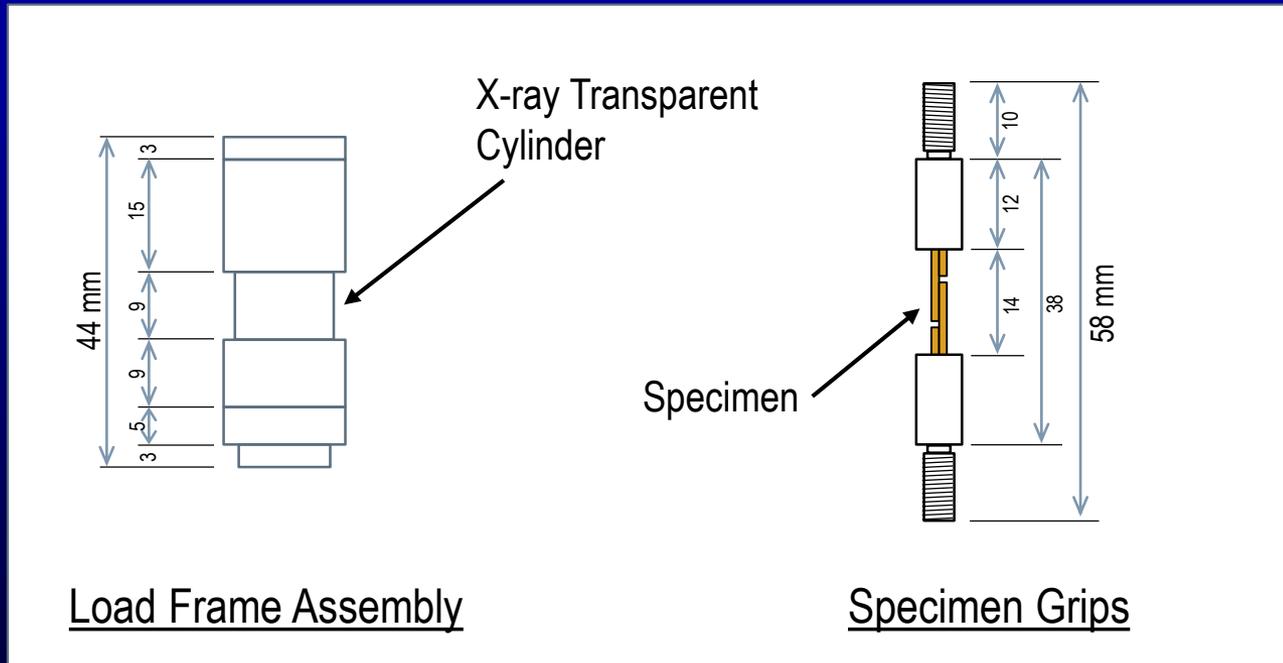
Specimens glued in grips

Test device designed and built by M. Zauner (Diss. ETH No. 21620)



In situ Micro-Bond Testing

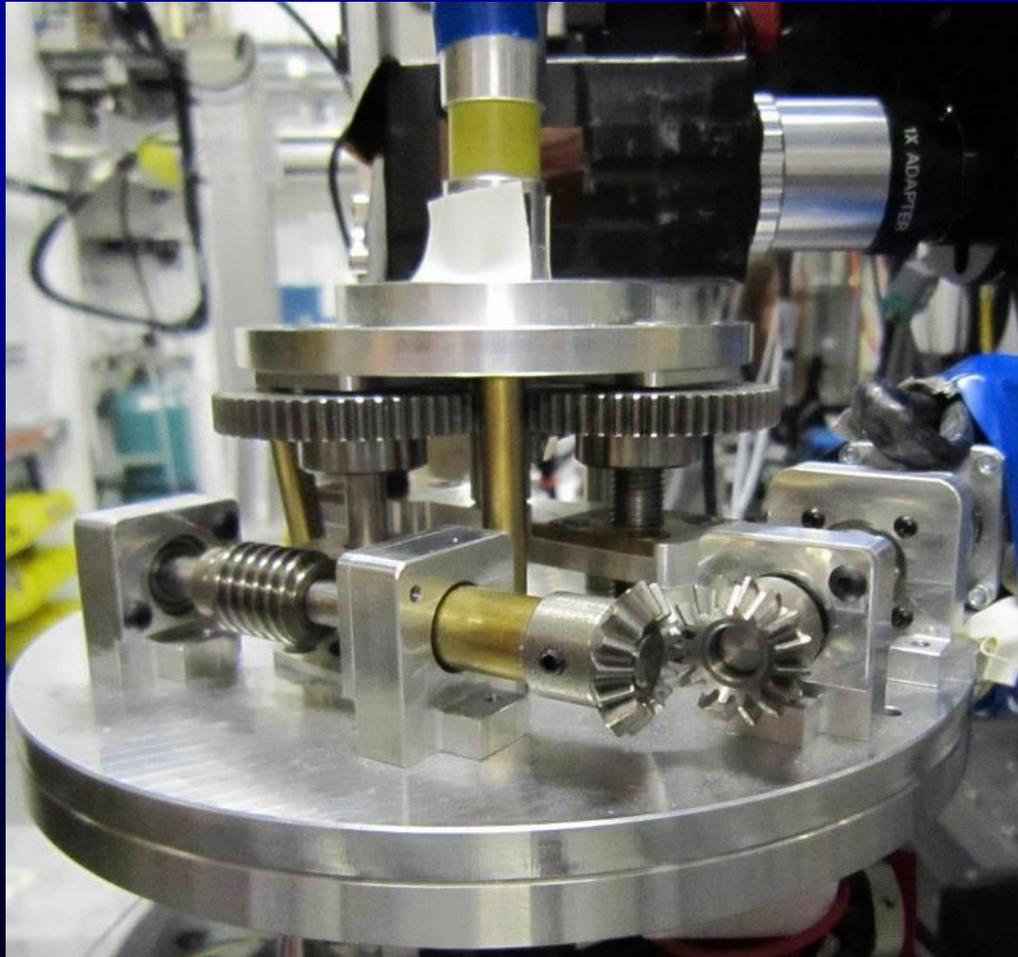
Destructive lap-shear test during step-wise XCT scan



Load Cell: +/- 100 N (+/- 0.1 N)
Displacement: 0.16 mm (+/- 0.0001 mm)

In situ Micro-Bond Testing

Destructive lap-shear test during step-wise XCT scan



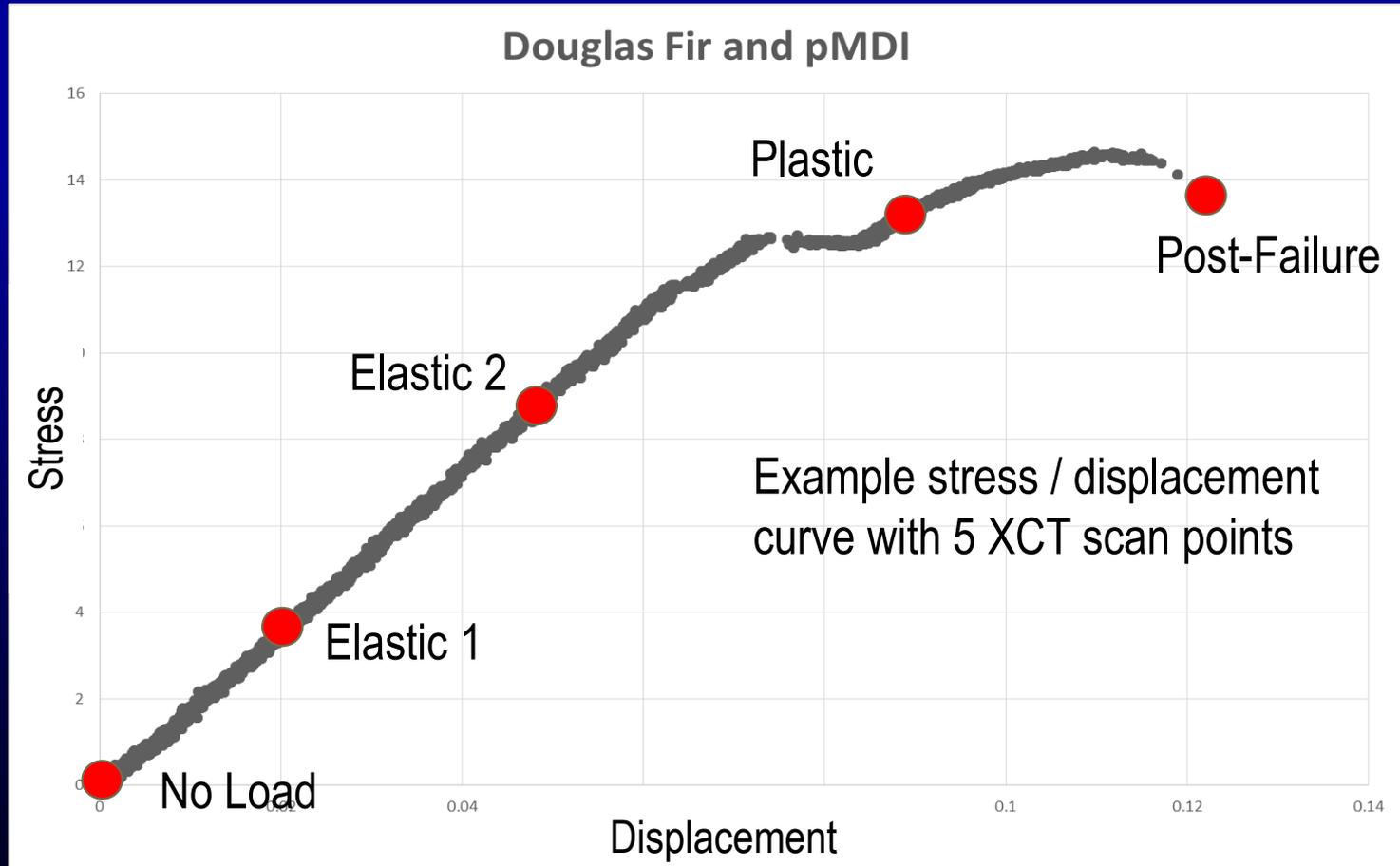
10 mm

Load Cell: +/- 1 kN (+/- 0.03 kN)

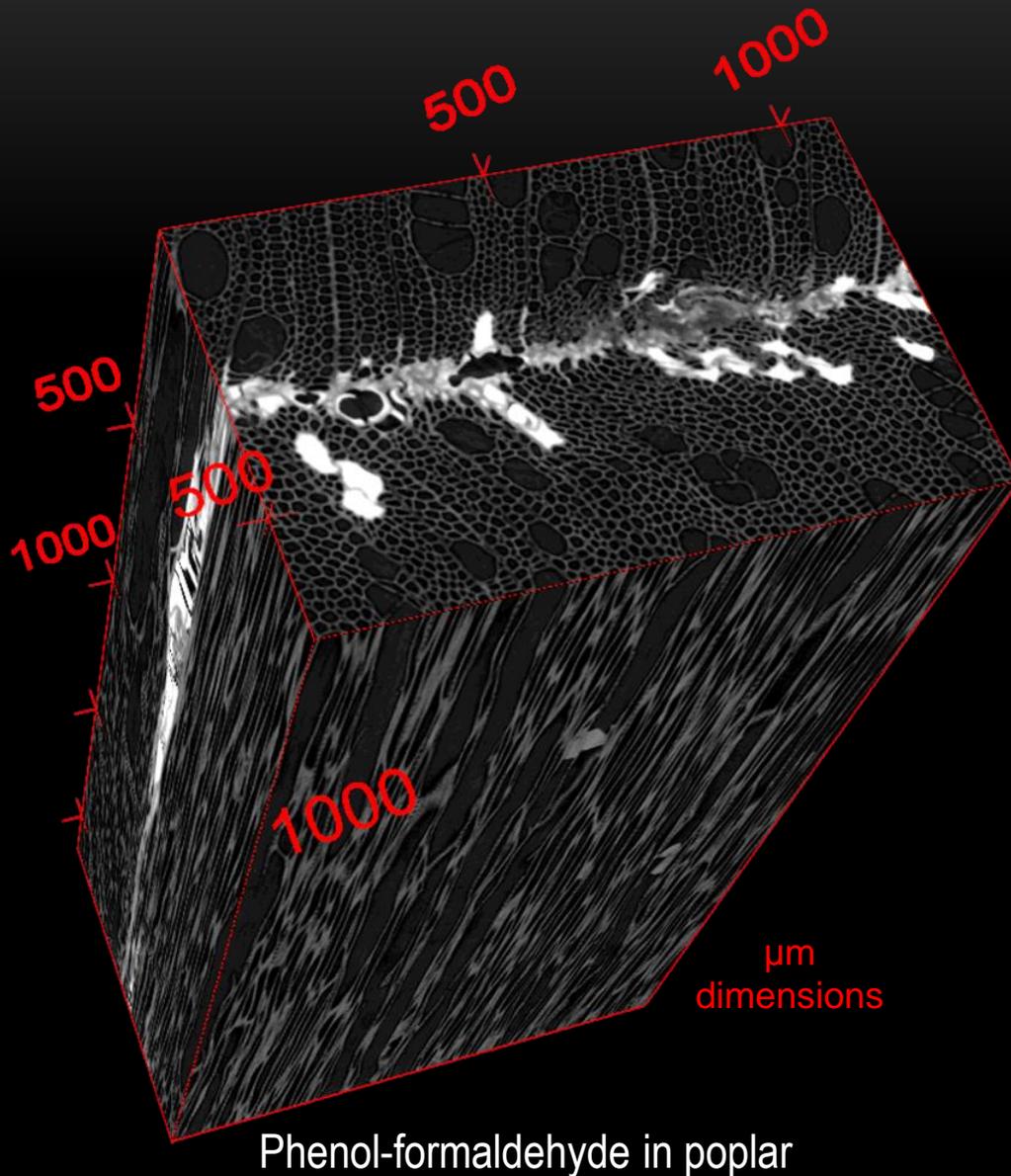
Displacement: 0.0002 mm/sec

In-situ Micro-Bond Testing

Step-wise XCT Scan



Segmentation

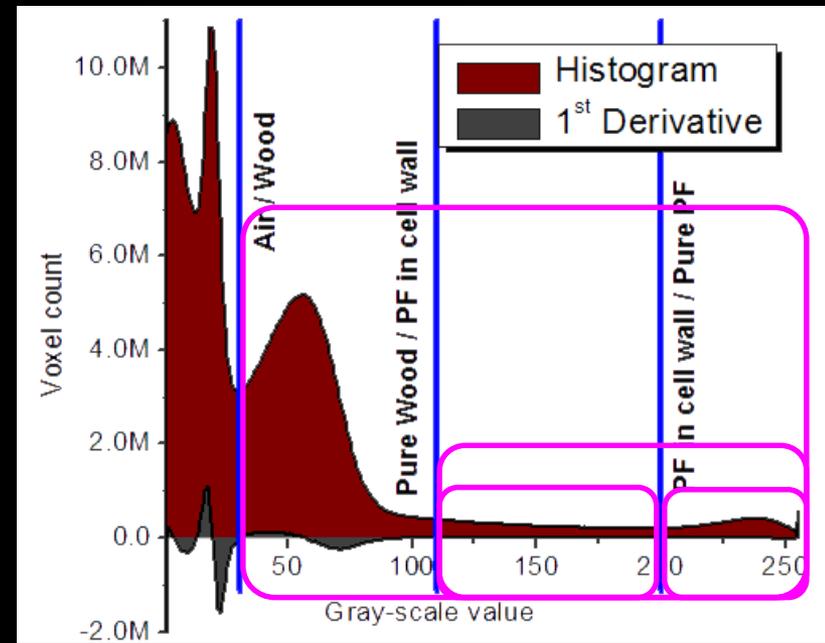


3 Materials for Segmentation

- Air (lumens)
- Wood cell walls
- Adhesive

Increasing attenuation
↓

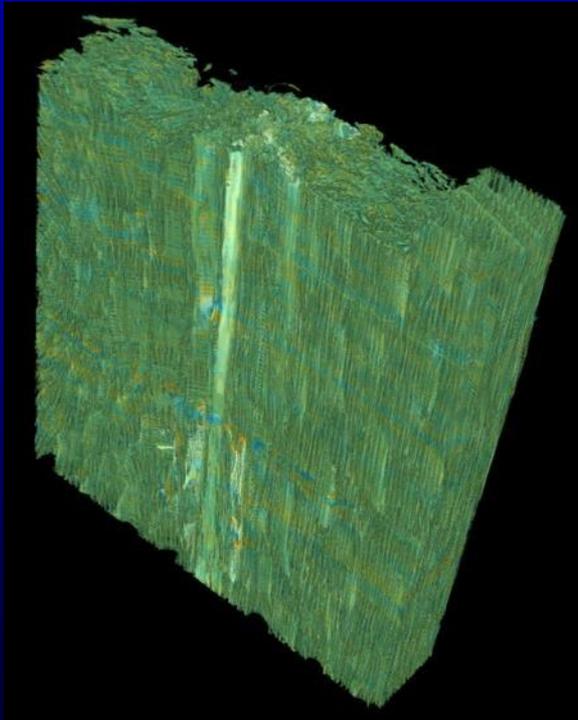
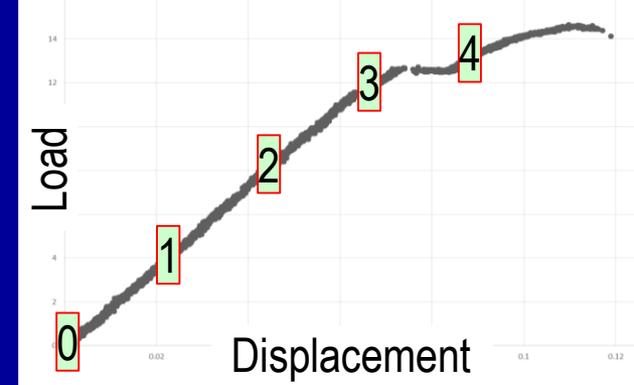
Gray-Scale Histogram of Voxels



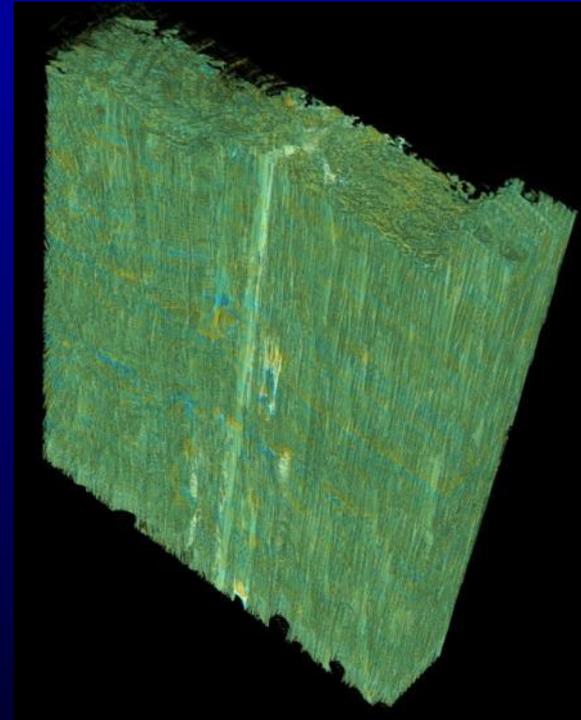
Increasing attenuation
→

Digital Volume Correlation

Douglas-fir bonded with PF adhesive



Strain Step 0 to 1

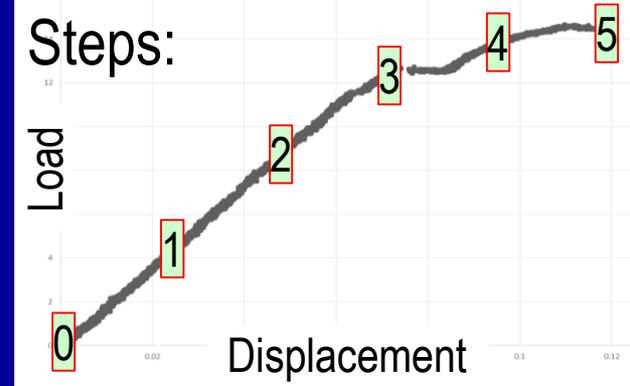
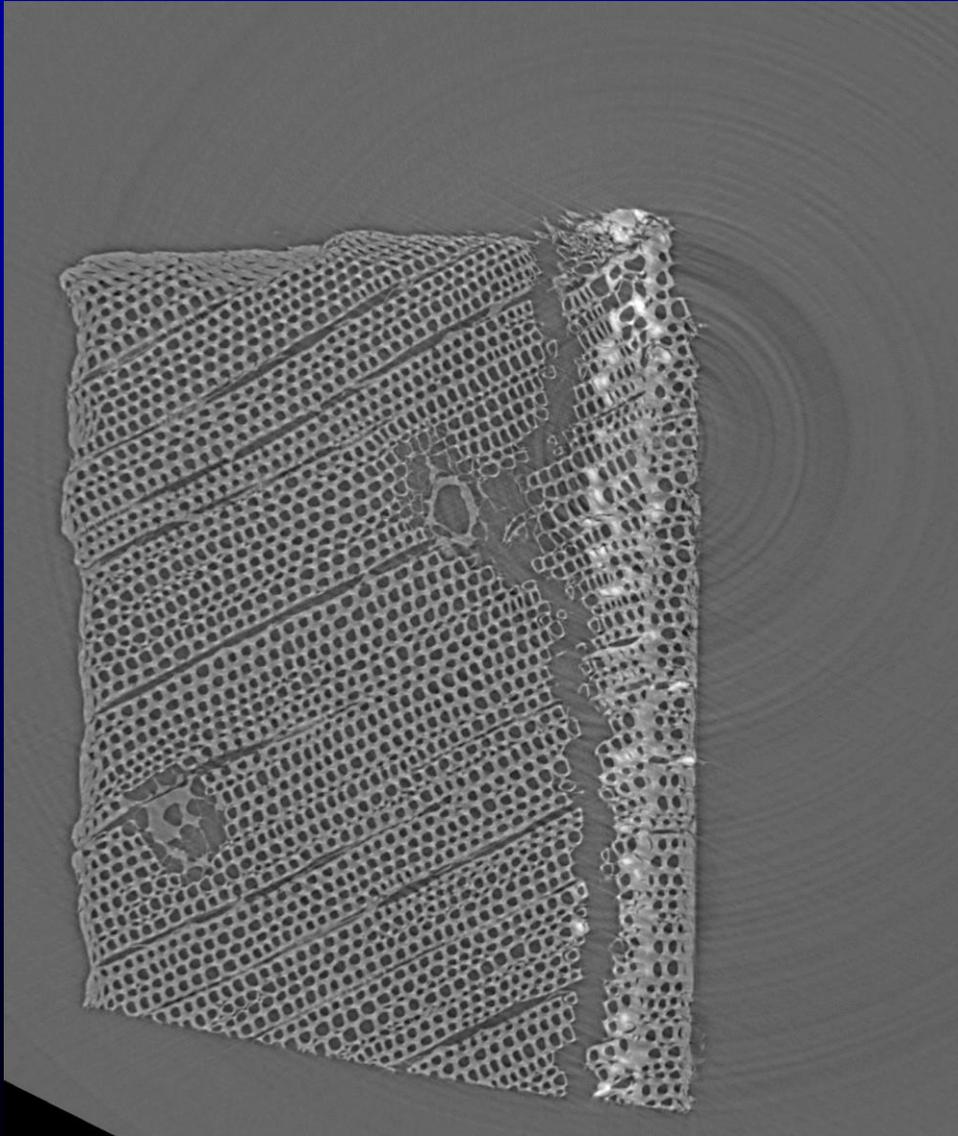


Strain Step 0 to 3

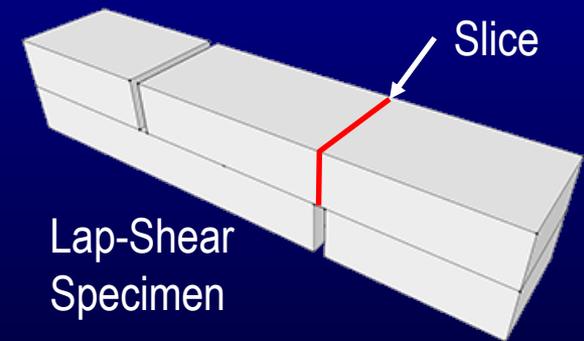


Method adapted from: Bar-Kochba E., et al. 2014. A fast iterative digital volume correlation algorithm for large deformations. Experimental Mechanics. DOI: 10.1007/s11340-014-9874-2

XCT & Lap-Shear Testing



Douglas-fir bonded with
PF adhesive



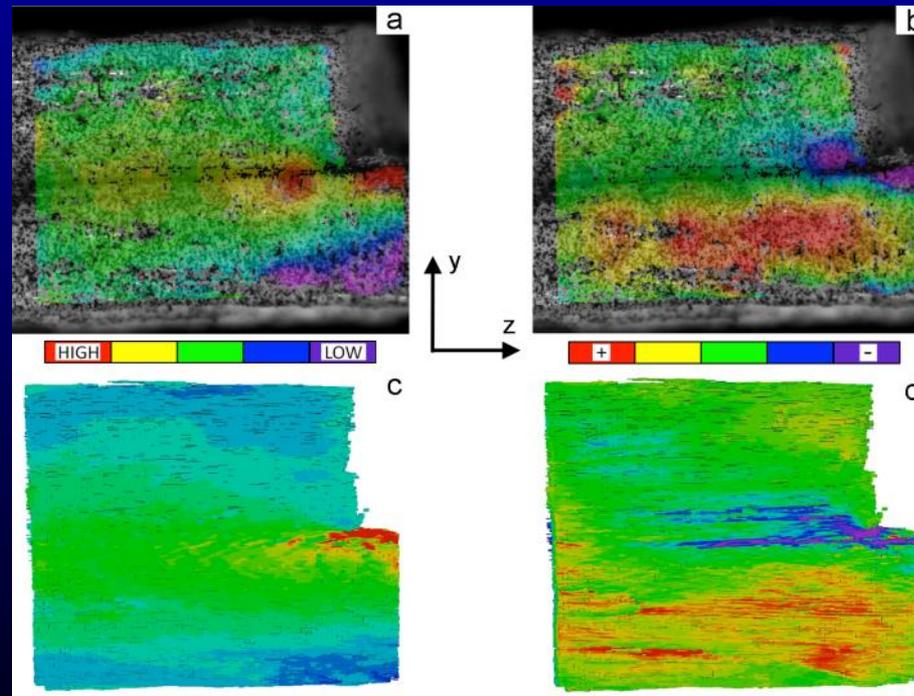
Step 5

Modeling by Material Point Method (MPM)

Physical system defined by voxels contained in tomogram (MPM model points), including material segmentation.

Material properties assigned to MPM points based on segmentation.

Micro-Bond Test

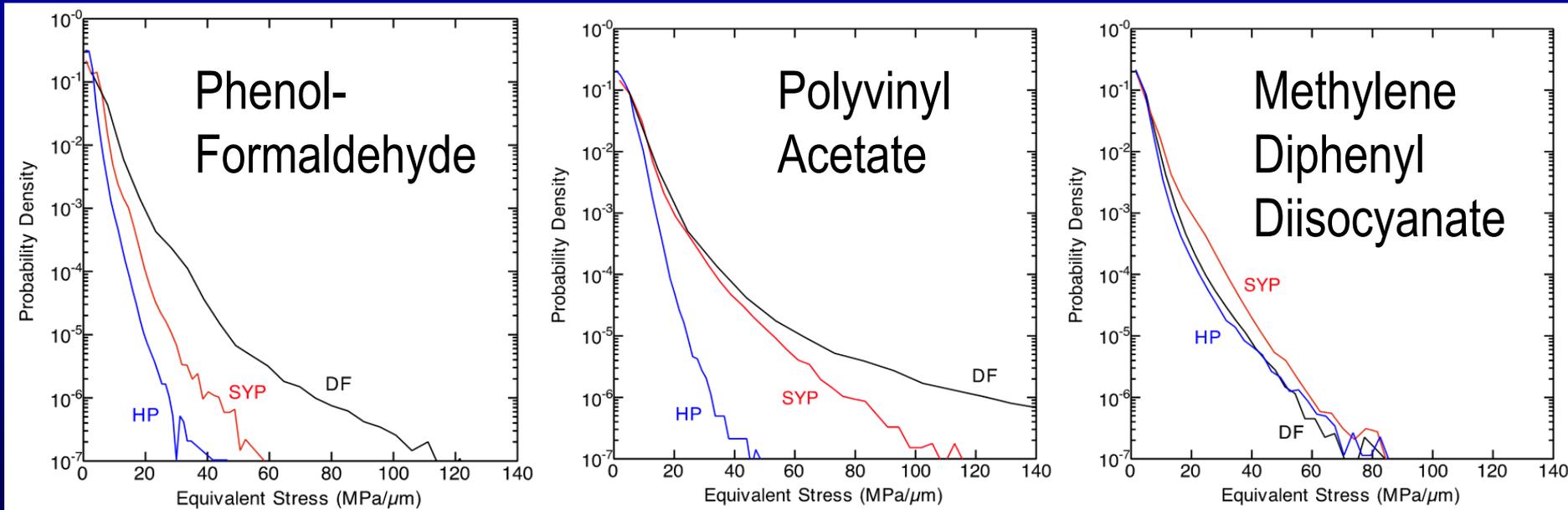


Model Simulation

Displacement

Shear Strain

Model Simulation of Bondline Shear Stress Probability Distribution of Local Stress in 3D Space



HP = Hybrid Poplar
SYP = Southern Pine
DF = Douglas-fir

- Higher probability of large local stress condition means bond is more likely to fail.
- Depends of adhesive penetration pattern, wood micro-structure, and adhesive modulus.

Acknowledgements



National Science Foundation

Industry/University Cooperative Research Center for Wood-Based Composites

